

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application:  
Rajeev Joshi et al.

Serial No.: 10/731,453

Filed: December 9, 2003

For: WAFER-LEVEL CHIP SCALE PACKAGE AND  
METHOD FOR FABRICATING AND USING THE  
SAME

Confirmation No. 4432

Group Art Unit: 2891

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Mail Stop Non-Final Response  
Commissioner for Patents  
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Sir:

**AMENDMENT AND REQUEST FOR RECONSIDERATION**

In response to the Office Action mailed July 16, 2008, Applicant requests reconsideration of this application in light of the following amendments and remarks.

**Amendments to the Claims** begin on page 2 of this paper.

**Remarks** begin on page 7 of this paper.